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2SD2115(L)/(S)

Silicon NPN Epitaxial Planar

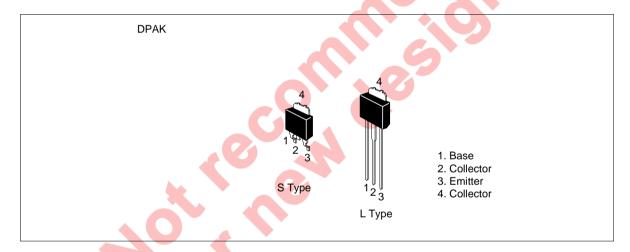


ADE-208-924 (Z) 1st. Edition September 2000

Application

Low frequency power amplifier

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	150	V
Collector to emitter voltage	V_{CEO}	60	V
Emitter to base voltage	V _{EBO}	5	V
Collector current	I _c	2	A
Collector peak current	I _{C(peak)}	2.5	A
Collector power dissipation	P _c *1	18	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

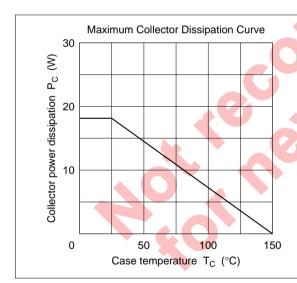
Note: 1. Value at $T_c = 25^{\circ}C$.

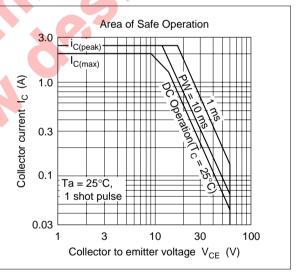
2SD2115(L)/(S)

Electrical Characteristics (Ta = 25°C)

Symbol	Min	Тур	Max	Unit	Test conditions
$V_{(BR)CBO}$	150	_	_	V	$I_{c} = 1 \text{ mA}, I_{E} = 0$
$V_{(BR)CEO}$	60	_	_	V	$I_{\rm C}$ = 10 mA, $R_{\rm BE}$ = ∞
$V_{(BR)EBO}$	5	_	_	V	$I_{E} = 1 \text{ mA}, I_{C} = 0$
I _{CBO}	_	_	10	μΑ	V _{CB} = 100 V, I _E = 0
h _{FE}	150	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 1.5 \text{ A}^{*1}$
$V_{\text{CE(sat)}}$	_	_	0.8	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 0.05 \text{ A}^{*1}$
$V_{BE(sat)}$	_	_	1.3	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 0.05 \text{ A}^{*1}$
t _f	_	_	0.6	μs	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 50 \text{ mA}$
	V _{(BR)CBO} V _{(BR)CBO} V _{(BR)EBO} I _{CBO} h _{FE} V _{CE(sat)} V _{BE(sat)}	V _{(BR)CBO} 150 V _{(BR)CBO} 60 V _{(BR)EBO} 5 I _{CBO} — h _{FE} 150 V _{CE(sat)} — V _{BE(sat)} —	V _{(BR)CBO} 150 — V _{(BR)CBO} 60 — V _{(BR)EBO} 5 — I _{CBO} — — h _{FE} 150 — V _{CE(sat)} — — V _{BE(sat)} — —	V _{(BR)CBO} 150 — V _{(BR)CEO} 60 — V _{(BR)EBO} 5 — I _{CBO} — — h _{FE} 150 — V _{CE(sat)} — 0.8	V _{(BR)CBO} 150 — V V _{(BR)CBO} 60 — V V _{(BR)EBO} 5 — V I _{CBO} — 10 μA h _{FE} 150 — — V _{CE(sat)} — 0.8 V V _{BE(sat)} — 1.3 V

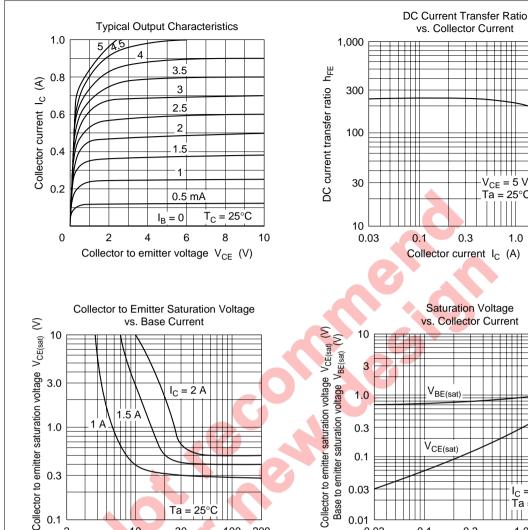
Note: 1. Pulse test.





 $V_{CE} = 5 V$ Ta = 25°C

3.0



 $I_C = \overline{2 A}$

Ta = 25°C

30

Base current I_B (mA)

200

100

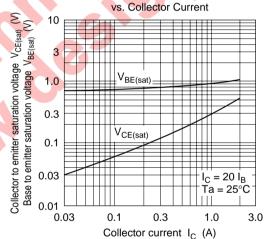
1.5 A

10

1.0

0.3

0.1 2



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